

DS3884 - 2.1 November 1998

Pythagoras Processor

SEIVIICUINDUCTUR

Supersedes version September 1996, DS3884 - 1.3

The PDSP16330 is a high speed digital CMOS IC that converts Cartesian data (Real and Imaginary) into Polar form (Magnitude and Phase), at rates up to 20MHz. Cartesian 16+16 bit 2's complement or Sign-Magnitude data is converted into 16 bit Phase format. The Magnitude output may be scaled in amplitude by powers of 2. The Phase output represents a full 2 x π field to eliminate phase ambiguities.

Polyimide is used as an inter-layer dielectric and as glassivation.

The PDSP16330 is offered in three speed grades: a basic 10MHz part (PDSP16330), a 20MHz version (PDSP16330A) and a 25MHz version (PDSP16330). A MIL-STD-883 version is also detailed in a separate datasheet.

FEATURES

- 25MHz Cartesian to Polar Conversion
- 16-Bit Cartesian Inputs
- 16-Bit Magnitude Output
- 12-Bit Phase Output
- 2's Complement or Sign-Magnitude Input Formats Three-state Outputs and Independent
- Data Enables Simplify System Interfacing
 Magnitude Scaling Facility with Overflow Flag
- Less than 400 mW Power Dissipation at 10MHz
- 84-pin PGA or 100 pin QFP Package or 84 LCC

APPLICATIONS

- Digital Signal Processing
- Digital Radio
- Radar Processing
- Sonar Processing
- Robotics

ORDERING INFORMATION

Commercial (0°C to +70°C	3)
PDSP16330A CO AC	(20MHZ - PGA Package)
PDSP16330B CO AC	(25MHZ - PGA Package)
Industrial (-40°C to +85°C)	Ĩ
PDSP16330A BO AC	20MHZ - PGA Package
PDSP16330A/IG/GC1R	20MHZ - GC Package
PDSP16330B BO AC	25MHZ - PGA Package
Military (-55°C to +125°C)	
PDSP16330A AO AC	20MHZ - PGA Package
PDSP16330/MC/GC1R	10MHz - GC Package
	Mil 883C Screened

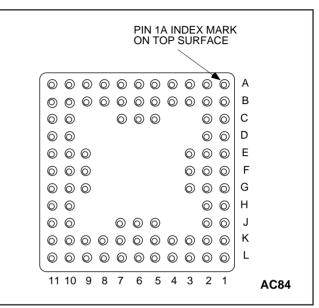


Fig.1 Pin connections - bottom view (PGA)

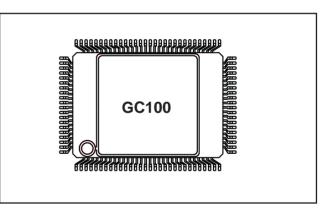


Fig.2 Pin connections - QFP Package

ASSOCIATED PPODUCTS

PDSP16112	16 X 12 Complex Multiplier
PDSP16116	16 X 16 Complex Multiplier
PDSP16318	Complex Accumulator
PDSP16350	I/Q Splitter and NCO
PDSP16510A	Stand Alone FFT Processor

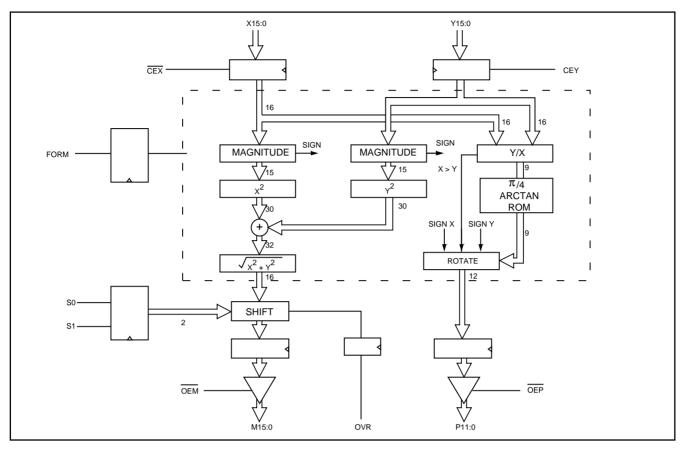


Fig.2 Block diagram

FUNCTIONAL DESCRIPTION

The PDSP16330 converts incoming Cartesian Data into the equivalent Polar Values. The device accepts new 16 + 16 bit complex data every cycle, and delivers a 16 bit + 12 bit Polar equivalent after 24 clock cycles. The input data can be in 2s' Complement or Sign Magnitude format selected via the FORM input. The output is in a magnitude format for both the Magnitude output and the Phase. Phase data is zero for data with a zero Y input and positive X, and is 400 hex for zero X data and positive Y, is 800 hex for zero Y data and negative X, and is C00 hex for zero X and negative Y. The LSB weighting (bit 0) is $2 \times \pi/4096$ radians. The 16 bit Magnitude result may be scaled by shifting one, two, or three places in the more significant direction, effectively multiplying the Magnitude result by 2,4 or 8 respectively. Any of these shifts can under certain conditions cause an invalid result to be output from the device. Under these circumstances the OVR output will become active. The PDSP16330 has independent clock enables and three state output controls for all ports.

FORM

This input selects the format of the X and Y input data. A low level on FORM indicates that the Input data is twos' complement format (Note: input data 8000 hex is not valid in 2s' complement mode). This input refers to the format of the current Input data and may be changed on a per cycle basis if desired. The level of FORM is latched at the same time as the data to which it refers.

S1-0

These inputs select the scaling factor to be applied to the Magnitude output. They are latched by the rising edge of CLK and determine the scaling of the output in the cycle after they are loaded into the device. The scale factor applied is determined by the table. Should the scaling factor applied cause an invalid Magnitude result to be output on the M Port, then the OVR Flag will become active for the period that the M Port output is invalid.

S1	S0	Scaling Factor
0	0	x1
0	1	x2
1	0	x4
1	1	x8

The output number range is from 0 to 2 when the scaling factor is set at x1.

PIN DESCRIPTIONS

Symbol	Pin Name and Description
CLK	Clock: Common Clock to device Registers. Register contents change on the rising edge of clock.
	Both pins must be connected.
CEX	Clock Enable: Clock Enable for X Port. The clock to the X port is enabled by a low level.
CEY	Clock Enable: Clock Enable for Y Port The clock to the Y port is enabled by a low level.
X15-X0	X Data Input Data presented to this input is loaded into the device by the rising edge of CLK. X15 is the MSB
Y15-Y0	Y Data Input Data presented to this input is loaded into the device by the rising edge of CLK. Y15 is the MSB
M15-M0	M Data Output: Magnitude data generated by the device is output on this port. Data changes on the rising edge of CLK, M15 is the MSB. The weighting of M15 is determined by the Scale factor selected.
P11-P0	P Data Output: Phase data generated by the device is output on this port. Data changes on the
	rising edge of CLK, P11 is the MSB. The weighting of P11 is π radians.
OEM	Output Enable: Output Enable for M Port. The M Port is in a high impedance state when this input
	is high.
OEP	Output Enable: Output Enable for P Port. The P Port is in a high impedance state when this input is high.
FORM	Format Select This input selects the format of the Cartesian Data input on the X and Y ports. This input is latched by the rising edge of CLK, and is applied at the same time as the data to which it refers. A low level indicates that two's complement data is applied, a high indicates Sign-Magnitude
S1-S0	Scaling Control: Control input for scaling of Magnitude Data. This input is latched by the rising edge of CLK, and determines the scaling to be applied to the Magnitude result. The Scaling is applied to the output data in the cycle following the cycle in which the control was latched.
OVR	Overflow: Overflow flag. This signal becomes active if the scaling currently selected causes an invalid value to be presented to the Magnitude output.
Vcc	+5V supply. All Vcc pins must be connected.
GND	0V supply. All GND pins must be connected.

2's Complement	Sign Magnitude
7FFF	7FFF
	•
0001 0000 FFFF	0001 0000 8000
8001	FFF

INPUT DATA RANGE

PIN FUNCTION

Pin No. AC	GC	Function	Pin No. AC	GC	Function	Pin No. AC	GC	Function
F3	91	M7	L9	23	YO	A9	59	X1
G3	92	M6	L10	24	CEY	B8	60	X2
G1	93	M5	K9	25	CLK	A8	61	X3
G2	94	M4	L11	26	Vcc	B6	62	X4
F1	95	M3	K10	31	GND	B7	63	X5
H1	96	M2	J10	32	GND	A7	64	X6
H2	97	M1	K11	33	GND	C7	65	X7
J1	98	MO	J11	34	GND	C6	66	X8
K1	99	S0	H10	35	GND	A6	67	X9
J2	100	S1	H11	36	GND	A5	68	X10
L1	1	GND	F10	37	GND	B5	69	X11
K2	6	Vcc	G10	38	OEP	C5	70	X12
K3	7	FORM	G11	39	P0	A4	71	X13
L2	8 9	Y15	G9	40	P1	B4	72	X14
L3		Y14	F9	41	P2	A3	73	X15
K4	10	Y13	F11	42	P3	A2	74	CLK
L4	11	Y12	E11	43	P4	B3	75	OVR
J5	12	Y11	E10	44	P5	A1	76	Vcc
K5	13	Y10	E9	45	P6	B2	81	GND
L5	14	Y9	D11	46	P7	C2	82	OEM
K6	15	Y8	D10	47	P8	B1	83	M15
J6	16	Y7	C11	48	P9	C1	84	M14
J7	17	Y6	B11	49	P10	D2	85	M13
L7	18	Y5	C10	50	P11	D1	86	M12
K7	19	Y4	A11	51	GND	E3	87	M11
L6	20	Y3	B10	52	Vcc	E2	88	M10
L8	21	Y2	B9	57	CEX	E1	89	M9
K8	22	Y1	A10	58	XO	F2	90	M8

ELECTRICAL CHARACTERISTICS

Test conditions (unless otherwise stated): T_{amb} (Commercial) = 0°C to + 70°C, T_{amb} (Industrial) = -40°C to + 85°C V_{cc} (Commercial) = 5.0V \pm 5%, V_{cc} (Industrial and Military) = 5.0V \pm 1%, GND = 0V

STATIC CHARACTERISTICS

Characteristic	Symbol	Value			Units	Sub- group	Conditions	
		Min.	Тур.	Max.		9 P		
* Output high voltage	V _{OH}	2.4			V	1,2,3	IOH = 3.2mA	
 Output low voltage 	V _{OL}			0.6	V	1,2,3	IOL=-3.2mA	
* Input high voltage (CMOS)	V _{IH}	3.0			V	1,2,3	Inputs CEX, CEY and CLK only	
* Input low voltage (CMOS)	V			1.0	V	1,2,3	Inputs CEX, CEY and CLK only	
* Input high voltage (TTL)	V _{IH}	2.2			V	1,2,3	All other inputs	
 Input low voltage (TTL) 	V _{IL}			0.8	V	1,2,3	All other inputs	
* Input leakage current (Note 1)	I _{IL}	-10		+ 120	μΑ	1,2,3	$GND \leq V_{IN} \leq V_{CC}$	
+ Input capacitance	Ċ _{IN}		10		pF			
* Output leakage current	I _{oz}	-50		+ 50	μA	1,2,3	$\text{GND} \leq V_{\text{IN}} \leq V_{\text{CC}}$	
† Output SC current	los	-50		230	mA		V _{cc} = Max	

NOTES

1. All inputs except clock inputs have high value pull-down resistors

2. All parameters marked * are tested during production. Parameters marked † are guaranteed by design and characterisation.

SWITCHING CHARACTERISTICS

			Va					
Characteristic	PDSP	16330	PDSP16330A		PDSP16330B		Units	Conditions
	Min.	Max.	Min.	Max.	Min.	Max.		
 Input data setup to clock rising edge Input data Hold after clock rising edge CEX, CEY Setup to clock rising edge CEX, CEY Hold aher clock rising edge FORM, S1:0 Setup to clock rising edge FORM, S1:0 Hold after clock rising edge Clock rising edge to valid data Clock period Clock high time Clock low time Latency OEM, OEP low to data high data valid OEM, OEP low to data high impedance Vcc current (TTL input levels) Vcc current (CMOS input levels) 	e 7 5 100 25 25 24	40 24 30 30 30 110 70	12 2 12 0 12 5 50 15 15 24	25 24 25 25 25 180 120	12 2 12 0 12 2 5 40 15 25 25 25 25 225 25 225	25 24	ns ns ns ns ns ns ns ns ns ns ns mA mA	$2 \times LSTTL + 20pF$ $2 \times LSTTL + 20pF$ $2 \times LSTTL + 20pF$ $2 \times LSTTL + 20pF$ $2 \times LSTTL + 20pF$ $V_{cc} = Max$ Outputs unloaded Clock freq. = Max $V_{cc} = Max$ Outputs unloaded Clock freq. = Max

NOTES

1. LSTTL is equivalent to $I_{OH} = 20\mu A$, $I_{OL} = -0.4mA$ 2. Current is defined as negative into the device 3. CMOS input levels are defined as: $V_{IH} = V_{DD} - 0.5V$, $V_{IL} = +0.5V$ 4. All parameters marked * are tested during production. Parameters marked † are guaranteed by design and characterisation. 5. All timings are dependent on silicon speed. This speed is tested by measuring clock period.

This guarantees all other timings by characterisation and design.

ABSOLUTE MAXIMUM RATINGS

Supply voltage, V _{cc}	-0.5V to + 7.0V
Input voltage, V _{IN}	-0.5V to VCC + 0.5V
Output voltage, V _{our}	-0.5V to VCC + 0.5V
Clamp diode current per pin, I _K (see N	lote 2) ±18mA
Static discharge voltage (HMB), V _{STAT}	500V
Storage temperature. T _{sta}	-65°C to + 150°C
Ambient temperature with	
power applied T _{amb} :	
Commercial	0°C to + 70°C
Industrial	-40°C to + 85°C
Military	-55 °C to + 125°C
Package power dissipation P _{TOT}	1200mW
Junction temperature	150°C

THERMAL CHARACTERISTICS

Package Type	<i>θ</i> JC° C/W	<i>θ</i> ja° C/W
AC	12	36
GC	12	35

NOTES

1. Exceeding these ratings may cause permanent damage. Functional operation under these conditions is not implied.

2. Maximum dissipation or 1 second should not be exceeded; only one output to be tested at any one time.

3. Exposure to Absoulte Maximum Ratings for extended periods may affect device reliability.

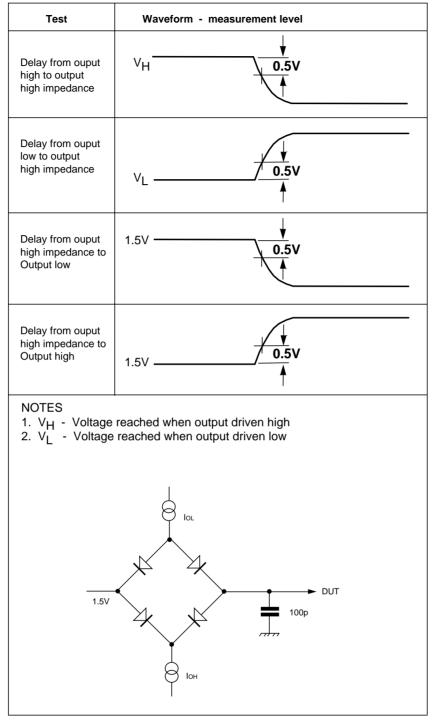


Fig.3 Three state delay measurement load

$ \begin{array}{c} 1\\ 2\\ 3\\ 4\\ 5\\ 6\\ 7\\ 8\\ 9\\ 10\\ 11\\ 12\\ 13\\ 14\\ 15\\ 16\\ 17\\ 18\\ 19\\ 20\\ 21\\ 22\\ 23\\ 24\\ 25\\ 26\\ 27\\ 28\\ \end{array} $	$\begin{array}{c c} \text{Cl} & \text{Cl}$	K 6 J 6 J 7 L 7 L 6 L 8 K 9 L 10 K 9 L 10 K 9 L 10 K 10 J 10 K 11 H 10 G 10 G 10 G 11 F 10 G 9 F 11 E 11 E 9 F 11 E 9 D 10	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	10 UN 2 LE PII AL 3 SE TC 4 IN & 5 P S	AD PLATING 60U INCHES MIN THICKN DUD PLATING 60U INCHES MIN THICKN OU INCHES NOMINAL THICKNESS OF ILESS OTHERWISE SPECIFIED IN PURC AD RESISTANCE: N NO. 11,32,53,740.250 MAX. L OTHERS0.50 MAX. L OTHERS0.50 MAX. L OTHERS0.50 MAX. L OTHERS0.50 MAX. L OTHERS	NICKEL CHASE ORDER AREAS ER DUS POSITIONS & DUS POSITIONS & DUS PURPOSES				Symbo H H1 H2 D D1 D2 E e 11 N ND ND ND NOTE	MIN MAX 3.35 4.14 1.93 2.39 1.14 1.40 27.64 28.24 1.14 1.40 0.41 0.51 27.64 28.24 1.45 2.54 4.45 4.70 Pin	Contro in MIN 0.13 0.07 0.04 1.08 0.04 0.01 1.08 0.17 features 84
© Mitel	1999 All i	rights res	erved.						ORIG	INATING S	ITE: Swind	on
ISSUE ACN DATE	1 207473 13SEP99				- MITEL	SEMI	CON	DUCTOR	Title: Drawir	ng Number	Drawing A (AC)	
APPRD.										GPD	00603)

Control Dimensions

 MIN
 MAX

 0.132
 0.163

 0.076
 0.094

 0.045
 0.055

 1.088
 1.112

 0.045
 0.055

0.016 0.020 1.088 1.112 0.100

Pin 1 Identifier A3	Control Dimensions Altern. Dimensions
Notes: 1. All dimensions and tolerances conform to ANSI Y14.5M-1982 2. Dimensions D1 and E1 do not include mould protrusions. Allowable mould protrusion is 0.010" per side. Dimensions D1 and E1 include mould protrusion is 0.010" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.101" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion is 0.100" per side. Dimensions D1 and E1 include mould protrusion per side. Dime	Symbol in inches in millimetres MIN MAX MIN MAX A 0.165 0.180 4.19 4.57 A1 0.090 0.120 2.29 3.05 A2 0.059 0.080 1.57 2.11 A3 0.042 0.056 1.07 1.42 A4 0.020 - 0.51 - D 1.185 1.195 30.10 30.35 D1 1.50 1.58 29.21 29.41 D2 0.541 0.569 13.74 14.45 E 1.185 1.195 30.10 30.35 E1 1.50 1.58 29.21 29.41 E2 0.541 0.569 13.74 14.45 B 0.026 0.032 0.66 0.81 b 0.013 0.021 0.33 0.53 e 0.050 BSC 1.27 BSC N 8
ISSUE 1 2	Title: Package Outline for
ACN 5958 207471 MITEL SEMICONDUCTOR	84 Lead PLCC
DATE 15AUG9410SEP99 APPD.	Drawing Number GPD00006
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